Docket No.: 1514.1030

COMBINED DECLARATION/POWER OF ATTORNEY FOR UTILITY/DESIGN PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

THIN FILM TRANSISTOR WITH LDD/OFFSET STRUCTURE

the specification of which is attached hereto, unless the following box is checked:

was filed on __ as United States Application Number or PCT International Application Number __ TO BE ASSIGNED_ and was amended on (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56.

I hereby claim foreign priority benefit(s) under 35 U.S.C. ' 119(a)-(d) or ' 365(a)-(c) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)			Priority NOT Claimed	
2002-80326	Republic of Korea	16/December/2002		
(Number)	(Country)	Day/Month/Year Filed	. 🗆	
	, , ,		П	
(Number)	(Country)	Day/Month/Year Filed		
designating the United States, listed be United States or PCT International app	elow and, insofar as the subject ma plication(s) in the manner provided to patentability as defined in 37 C.F	d States application(s), or ' 365(c) of any PCT latter of each of the claims of this application is reby the first paragraph of 35 U.S.C. ' 112, I ack F.R. ' 1.56 which became available between the tion.	ot disclosed in the prior nowledge the duty to	
(Application Serial No.)	(Filing Date)	(Status patented, pending,	abandoned)	
(Application Serial No.)	(Filing Date)	(Status patented, pending,	abandoned)	
I hereby appoint the attorneys and agents of Staas & Halsey LLP under USPTO Customer No. 21,171 to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:				
21171 PATENT TRADEMARK OFFICE				
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.				
Full name of sole or first inventor				
Inventor's Signature	your Park	Date <u>December 3, 200</u>	03	
Residence Suwon-city, Korea		Citizenship Republic of Korea		
Mailing Address_204, 993-5, Youngtong-dong, Paldal-gu, Suwon-city, Gyeonggi-do, Korea				
Full name of second inventor Ki Y	ong LEE			
1				
Inventor's Signature	Jos Tee	Date December 3, 200	03	
Residence Yongin-city, Korea	<i>U</i>	Citizenship Republic of Korea		

Mailing Address 101-1406, Dongseong Apt., Kiheung-eup, Yongin-city, Gyeonggi-do, Korea

Additional inventors are being named on separately numbered sheets attached hereto.

UNITED STATES

Docket No.: 1514.1030

COMBINED DECLARATION/POWER OF ATTORNEY FOR UTILITY/DESIGN PATENT APPLICATION

Full name of third inventor Hye Hyang PARK	
Inventor's Signature Hye Hyang Park	DateDecember 3, 2003
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Full name of fourth inventor	
Inventor's Signature	Date
Residence	
Mailing Address	
Full name of fifth inventor	
Inventor's Signature	Date
Residence	
Mailing Address	
Full name of sixth inventor	
Inventor's Signature	Date
Residence	
Mailing Address	
Full name of seventh inventor	
Inventor's Signature	Date
Residence	
Mailing Address	
Full name of eighth inventor	
Inventor's Signature	Date
Residence	
Mailing Address	
Full name of ninth inventor	
Inventor's Signature	Date
Residence	
Mailing Address	